

**FEE TRANSMITTAL**

Electronic Version v08

Stylesheet Version v08.0

**Title of  
Invention**

ALL-IN-ONE POLISHING PROCESS FOR A SEMICONDUCTOR WAFER

Application Number :

Date :

First Named Applicant: Mu-Liang Liao

Attorney Docket Number: NAUP0511USA

**TOTAL FEE AUTHORIZED \$ 882**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

**BASIC FILING FEE**

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

**EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 24	4	1202	18	72
Independent Claims : 3	0	1201	86	0
Subtotal For Extra Claims Fees: \$ 72				

**ASSIGNMENT FEES**

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

**AUTHORIZED BILLING INFORMATION****The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Deposit account number: 500801

Access Code \*\*\*\*\*

Deposit name: NORTH AMERICA INTERNATIONAL PATENT OFFICE

Deposit authorized name: WINSTON HSU

Signature: VAEB-JMXX-8IIL

Date (YYYYMMDD): 2004-01-15

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.